

Method for treating substrates

Abstract

The invention relates to a method for treating substrates comprising: a step of treating a first substrate comprising at least one step carried out in an apparatus carrying out a thermal treatment, the first substrate being a substrate made of a semiconductor material or of a piezoelectric material; a step of decontaminating the apparatus carrying out a thermal treatment by a thermal treatment of a decontamination substrate, in particular a silicon substrate; and then a step of treating a second substrate comprising at least one step carried out in the apparatus carrying out a thermal treatment, the first substrate being a substrate made of a semiconductor material or of a piezoelectric material.

Fig. 1